

**SCOPE: 12-BIT A/D CONVERTER**

<u>Device Type</u>	<u>Generic Number</u>
01	MX674ASQ/883B
02	MX674ATQ/883B
03	MX674AUQ/883B

**Case Outline(s).** The case outlines shall be designated in Mil-Std-1835 and as follows:

<u>Outline Letter</u>	<u>Mil-Std-1835</u>	<u>Case Outline</u>	<u>Package Code</u>
Q X	GDIP1-T28 or CDIP2-T28	28 Lead CERDIP	J28

**Absolute Maximum Ratings**

$V_{CC}$ to DGND .....	0V to +16.5V
$V_{EE}$ to DGND .....	0V to -16.5V
$V_L$ to DGND .....	0V to +7V
DGND to AGND .....	$\pm 1V$
Control Inputs to DGND (CE, A0, 12/8, R/C, CS) .....	-0.3V to $V_{CC} + 0.3V$
Digital Output Voltage to DGND(DB11-DB0, STS) .....	-0.3V to $V_L + 0.3V$
Analog Inputs (REF IN, BIP OFF, 10 $V_{IN}$ ) to AGND .....	$\pm 16.5V$
20 $V_{IN}$ analog input voltage to AGND .....	$\pm 24V$
REF OUT .....	Indefinite short to $V_{CC}$ or AGND
Lead Temperature (soldering, 10 seconds) .....	+300°C
Storage Temperature .....	-65°C to +160°C
Continuous Power Dissipation .....	$T_A = +70^\circ C$
28 pin CERDIP (derate 16.7mW/°C above +70°C) .....	1333mW
Junction Temperature $T_J$ .....	+150°C
Thermal Resistance, Junction to Case, $\theta_{JC}$ 28 pin CERDIP .....	25°C/W
Thermal Resistance, Junction to Ambient, $\theta_{JA}$ : 28 pin CERDIP .....	60°C/W

**Recommended Operating Conditions**

Ambient Operating Range ( $T_A$ ) .....	-55°C to +125°C
$V_L$ .....	+5V
$V_{CC}$ .....	+15V or +12V
$V_{EE}$ .....	-15V or -12V

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TABLE 1. ELECTRICAL TESTS:**

TEST	Symbol	CONDITIONS	Group A Subgroup	Device type	Limits Min	Limits Max	Units
		-55 °C ≤ T <sub>A</sub> ≤ +125°C V <sub>CC</sub> =+15V or +12V, V <sub>LOGIC</sub> =5V, V <sub>EE</sub> =-15V or -12V Unless otherwise specified					
<b>ACCURACY</b>							
Resolution	RES		1	All	12		Bits
Integral Nonlinearity	INL		1,2,3	01		±1.0	LSB
			1 2,3	02,03		±0.5 ±0.75	
Differential Nonlinearity	DNL	12 bits, no missing codes over temp.	1	All		±1.0	LSB
Unipolar Offset Error		NOTE 1	1	01		±2.0	LSB
				02,03		±1.0	
Bipolar Offset Error		NOTES 2, 3	1	01,02		±4.0	LSB
				03		±2.0	
Full-Scale Calibration Error		NOTE 3	1	All		0.25	%
<b>TEMPERATURE COEFFICIENTS</b>							
Using Internal Reference NOTES 2, 3, 4							
Unipolar Offset Change			1,2,3	01		±2.0	LSB
				02,03		±1.0	
Bipolar Offset Change			1,2,3	01		±4.0	LSB
				02		±2.0	
				03		±1.0	
Full-Scale Calibration Change			1,2,3	01		±20	LSB
				02		±10	
				03		±5	
<b>INTERNAL REFERENCE</b>							
Output Voltage		No Load	1	01,02 03	9.97 9.99	10.03 10.01	V
Output Current		Available for external loads, in addition to REFIN and BIPOFF load. NOTE 5	1	All		2.0	mA
<b>ANALOG INPUT</b>							
Bipolar Input Range		Using 10V input	1	All		±5	V
		Using 20V input				±10	
Unipolar Input Range		Using 10V input	1	All		0	V
		Using 20V input				0	
Input Impedance		10V input	1	All		3	kΩ
		20V input				6	
<b>POWER-SUPPLY REJECTION</b>							
Max change in Full-scale calibration							
V <sub>CC</sub> only		+15V±1.5V or +12V±0.6V	1	01		±2	LSB
				02,03		±1	
V <sub>EE</sub> only		-15V±1.5V or -12V±0.6V	1	All		±0.5	LSB
V <sub>L</sub> only		+5V±0.5V	1	All		±0.5	LSB

TEST	Symbol	CONDITIONS		Limits Min	Limits Max	Units
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<b>LOGIC INPUTS</b>						
Input Low Voltage	V <sub>IL</sub>	$\overline{\text{CS}}, \overline{\text{CE}}, \overline{\text{R/C}}, \text{A0}, 12/\overline{8}$	1	All	0.8	V
Input High Voltage	V <sub>IH</sub>	$\overline{\text{CS}}, \overline{\text{CE}}, \overline{\text{R/C}}, \text{A0}, 12/\overline{8}$	1	All	2.0	V
Input Current	I <sub>IN</sub>	$\overline{\text{CS}}, \overline{\text{CE}}, \overline{\text{R/C}}, \text{A0}, 12/\overline{8}$ , VIN=0 to V <sub>L</sub>	1	All	±5	μA
<b>LOGIC OUTPUTS</b>						
Output Low Voltage	V <sub>OL</sub>	DB11-DB0, STS, I <sub>SINK</sub> =1.6mA	1	All	0.4	V
Output High Voltage	V <sub>OH</sub>	DB11-DB0, STS, I <sub>SOURCE</sub> =500μA	1	All	4.0	V
Floating State Leakage Current	I <sub>LKG</sub>	DB11-DB0, STS, V <sub>OUT</sub> =0 to V <sub>L</sub>	1	All	±10	μA
<b>CONVERSION TIME</b>						
12-Bit Cycle	t <sub>CONV</sub>		9	All	9	15 μs
8-Bit Cycle	t <sub>CONV</sub>		9	All	6	11 μs
<b>POWER REQUIREMENTS</b>						
V <sub>CC</sub> Operating Range			1	All	11.4	16.5 V
V <sub>L</sub> Operating Range			1	All	4.5	5.5 V
V <sub>EE</sub> Operating Range			1	All	-11.4	-16.5 V
V <sub>CC</sub> Supply Current	I <sub>CC</sub>	NOTE 5	1	All		5 mA
V <sub>L</sub> Supply Current	I <sub>L</sub>	NOTE 5	1	All		8 mA
V <sub>EE</sub> Supply Current	I <sub>EE</sub>	NOTE 5	1	All		10 mA
Power Dissipation	P <sub>D</sub>	V <sub>CC</sub> =+15V and V <sub>EE</sub> =-15V NOTE 5	1	All		265 mW
<b>CONVERT START TIMING</b>						
		<b>FULL CONTROL MODE</b> <b>NOTE 6</b>				
STS Delay from CE	t <sub>DSC</sub>	CL=50pF	9 10,11	All		200 320 ns
CE Pulse Width	t <sub>HEC</sub>		9,10,11	All	50	ns
$\overline{\text{CS}}$ to CE Setup	t <sub>SSC</sub>		9,10,11	All	50	ns
$\overline{\text{CS}}$ Low During CE high	t <sub>HSC</sub>		9,10,11	All	50	ns
$\overline{\text{R/C}}$ to CE Setup	t <sub>SRC</sub>		9,10,11	All	50	ns
$\overline{\text{R/C}}$ Low During CE high	t <sub>HRC</sub>		9,10,11	All	50	ns
A0 to CE Setup	t <sub>SAC</sub>		9,10,11	All	0	ns
A0 Valid During CE high	t <sub>HAC</sub>		9,10,11	All	50	ns
<b>READ TIMING</b>						
		<b>FULL CONTROL MODE 6/</b>				
Access Time (from CE)	t <sub>DD</sub>	CL=100pF	9 10,11	All		120 200 ns

TEST	Symbol	CONDITIONS	Group A Subgroup	Device type	Limits Min	Limits Max	Units
		-55 °C ≤ T <sub>A</sub> ≤ +125°C V <sub>CC</sub> =+15V or 12V, V <sub>LOGIC</sub> =5V, V <sub>EE</sub> =-15V or -12V Unless otherwise specified					
Data Valid after CE low	t <sub>HD</sub>		9 10,11	All	25 15		ns
Output Float Delay	t <sub>HL</sub>		9 10,11	All		75 120	ns
$\bar{CS}$ to CE Setup	t <sub>SSR</sub>		9,10,11	All	50		ns
$\bar{R/C}$ to CE Setup	t <sub>SRR</sub>		9,10,11	All	0		ns
A0 to CE Setup	t <sub>SAR</sub>		9,10,11	All	50		ns
$\bar{CS}$ to Valid after CE Low	t <sub>HSR</sub>		9,10,11	All	0		ns
$\bar{R/C}$ High After CE Low	t <sub>HRR</sub>		9,10,11	All	0		ns
A0 Valid After CE Low	t <sub>HAR</sub>		9,10,11	All	0		ns
<b>STAND-ALONE MODE</b>		<b>NOTE 6</b>					
Low $\bar{R/C}$ Pulse Width	t <sub>HRL</sub>		9,10,11	All	50		ns
STS Delay from $\bar{R/C}$	t <sub>DS</sub>		9 10,11	All		200 320	ns
Data Valid from $\bar{R/C}$ Low	t <sub>HDR</sub>		9 10,11	All	25 15		ns
STS Delay After Data Valid	t <sub>HS</sub>		9,10,11	All	30	600	ns
High $\bar{R/C}$ Pulse Width	t <sub>HRRH</sub>		9 10,11	All	150 200		ns
Data Access Time	t <sub>DDR</sub>	C <sub>L</sub> =100pF	9 10,11	All		120 200	ns

NOTE 1: Adjustable to zero

NOTE 2: With 50Ω fixed resistor from REFOUT to BIPOFF. Adjustable to zero.

NOTE 3: With 50Ω fixed resistor from REFOUT to REFIN. Adjustable to zero.

NOTE 4: Maximum change in specification from T<sub>A</sub>=+25°C to T<sub>MIN</sub> or T<sub>A</sub>=+25°C to T<sub>MAX</sub>.

NOTE 5: External load current should not change during a conversion. For ±12V supply operation, REFOUT need not be buffered except when external load in addition to REFIN and BIPOFF inputs have to be driven.

NOTE 6: Timing specifications guaranteed by design. All input control signals specified with tr=tf=5ns (10% to 90% of +5V) and timed from a voltage level of +1.6V. See loading circuits in Figures 1 and 2 in the Commercial data sheet.

	Package	ORDERING INFORMATION:
01	28 pin CERDIP	MX674ASQ/883B
02	28 pin CERDIP	MX674ATQ/883B
03	28 pin CERDIP	MX674AUQ/883B

TRUTH TABLE:					
CE	$\overline{\text{CS}}$	$\overline{\text{R/C}}$	$\overline{12/8}$	A0	OPERATION
0	X	X	X	X	None
X	1	X	X	X	None
1	0	0	X	0	Initiate 12-bit conversion
1	0	0	X	1	Initiate 8-bit conversion
1	0	1	1	X	Enable 12-bit parallel output
1	0	1	0	0	Enable 8 most significant bits
1	0	1	0	1	Enable 4 LSBs +4 trailing zeros

**TERMINAL CONNECTIONS:**

	J28		
1	V <sub>LOG</sub>	15	DGND
2	$\overline{12/8}$	16	DB0
3	$\overline{\text{CS}}$	17	DB1
4	A0	18	DB2
5	$\overline{\text{R/C}}$	19	DB3
6	CE	20	DB4
7	V <sub>CC</sub>	21	DB5
8	REF OUT	22	DB6
9	AGND	23	DB7
10	REFIN	24	DB8
11	V <sub>EE</sub>	25	DB9
12	BIP OFF	26	DB10
13	10 V <sub>IN</sub>	27	DB11(MSB)
14	20 V <sub>IN</sub>	28	STS

## QUALITY ASSURANCE

Sampling and inspection procedures shall be in accordance with MIL-Prf-38535, Appendix A as specified in Mil-Std-883.

Screening shall be in accordance with Method 5004 of Mil-Std-883. Burn-in test Method 1015:

1. Test Condition, A, B, C, or D.
2. TA = +125°C minimum.
3. Interim and final electrical test requirements shall be specified in Table 2.

Quality conformance inspection shall be in accordance with Method 5005 of Mil-Std-883, including Groups A, B, C, and D inspection.

Group A inspection:

1. Tests as specified in Table 2.
2. Selected subgroups in Table 1, Method 5005 of Mil-Std-883 shall be omitted.

Group C and D inspections:

- a. End-point electrical parameters shall be specified in Table 1.
- b. Steady-state life test, Method 1005 of Mil-Std-883:
  1. Test condition A, B, C, D.
  2. TA = +125°C, minimum.
  3. Test duration, 1000 hours, except as permitted by Method 1005 of Mil-Std-883.

**TABLE 2. ELECTRICAL TEST REQUIREMENTS**

Mil-Std-883 Test Requirements	Subgroups per Method 5005, Table 1
Interim Electric Parameters Method 5004	1
Final Electrical Parameters Method 5005	1*, 2, 3, 9**, 10**, 11**
Group A Test Requirements Method 5005	1, 2, 3, 9**, 10**, 11**
Group C and D End-Point Electrical Parameters Method 5005	1

\* PDA applies to Subgroup 1 only.

\*\* Subgroups 10 and 11, if not tested shall be guaranteed to the specified limits of Table 1.  
Conversion Time is tested for Subgroup 9 and Timing Specifications are guaranteed by design.